





### SURFACE MOUNT SWITCHING DIODE ARRAY

### **Features**

- Fast Switching Speed
- Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance
- Two "BAV99" Circuits In One Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Notes 3 & 4)
- Qualified to AEC-Q101 Standards for High Reliability

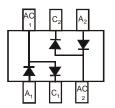
### **Mechanical Data**

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)

**SOT363** 



Top View



Top View Internal Schematic

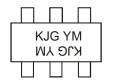
## Ordering Information (Note 5)

| Part Number  | Case   | Packaging         |
|--------------|--------|-------------------|
| BAV99DW-7-F  | SOT363 | 3000/Tape & Reel  |
| BAV99DW-13-F | SOT363 | 10000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb<sub>2</sub>O<sub>3</sub> Fire Retardants.
- 5. For packaging details, go to our website at http://www.diodes.com.

## **Marking Information**



KJG = Product Type Marking Code YM = Date Code Marking Y = Year (ex: N = 2002) M = Month (ex: 9 = September)

Date Code Key

| Year  | 2001 | 2002 | 2003 | 2004 |     | 2012 | 2013 | 2014 | 2015 | 2016 | 2017 | 2018 |
|-------|------|------|------|------|-----|------|------|------|------|------|------|------|
| Code  | М    | N    | Р    | R    |     | Z    | Α    | В    | С    | D    | Е    | F    |
|       |      |      |      |      |     |      |      |      |      |      |      |      |
| Month | Jan  | Feb  | Mar  | Apr  | May | Jun  | Jul  | Aug  | Sep  | Oct  | Nov  | Dec  |



## Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

| Characteristic   | Symbol   | Value            | Unit              |   |
|--|--|------------------|-------------------|---|
| Non-Repetitive Peak Reverse Voltage  | $V_{RM}$   | 100              | V                 |   |
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage | V <sub>RRM</sub><br>V <sub>RWM</sub><br>V <sub>R</sub> | 75               | V                 |   |
| RMS Reverse Voltage  | $V_{R(RMS)}$   | 53               | V                 |   |
| Forward Continuous Current (Note 6)  | I <sub>FM</sub>  | 215              | mA                |   |
| Non-Repetitive Peak Forward Surge Current  | @ t = 1.0μs<br>@ t = 1.0ms<br>@ t = 1.0s               | I <sub>FSM</sub> | 2.0<br>1.0<br>0.5 | А |

### **Thermal Characteristics**

| Characteristic                                      | Symbol                            | Value       | Unit |
|---|-----------------------------------|-------------|------|
| Power Dissipation (Note 6)                          | P <sub>D</sub>                    | 200         | mW   |
| Power Dissipation (Note 7)                          | $P_{D}$                           | 300         | mW   |
| Thermal Resistance Junction to Ambient Air (Note 6) | $R_{	hetaJA}$                     | 625         | °C/W |
| Thermal Resistance Junction to Ambient Air (Note 7) | $R_{	heta JA}$                    | 417         | °C/W |
| Operating and Storage Temperature Range             | T <sub>J</sub> , T <sub>STG</sub> | -65 to +150 | °C   |

# Electrical Characteristics @TA = 25°C unless otherwise specified

| Characteristic                     | Symbol             | Min | Max   | Unit       | Test Condition   |
|------------------------------------|--------------------|-----|-------|------------|--|
| Reverse Breakdown Voltage (Note 8) | V <sub>(BR)R</sub> | 75  | 1     | >          | $I_R = 2.5 \mu A$  |
|                                    |                    | _   | 0.715 |            | $I_F = 1.0 \text{mA}$  |
| Forward Voltage                    | VF                 | _   | 0.855 | V          | I <sub>F</sub> = 10mA  |
| Tolward Vollage                    | ٧F                 | _   | 1.0   |            | $I_F = 50 \text{mA}$   |
|                                    |                    | _   | 1.25  |            | I <sub>F</sub> = 150mA   |
|                                    |                    | _   | 2.5   | μΑ         | $V_R = 75V$  |
| Reverse Current (Note 8)           | I_                 | _   | 50    | μ <b>A</b> | $V_R = 75V, T_J = +150^{\circ}C$   |
| Reverse Current (Note 6)           | I <sub>R</sub>     | _   | 30    | μΑ         | $V_R = 25V, T_J = +150^{\circ}C$   |
|                                    |                    | _   | 25    | nA         | $V_R = 20V$  |
| Total Capacitance                  | CT                 | _   | 2.0   | рF         | $V_R = 0, f = 1.0MHz$  |
| Reverse Recovery Time              | t <sub>rr</sub>    | _   | 4.0   | ns         | $I_F = I_R = 10 \text{mA},$<br>$I_{rr} = 0.1 \text{ x } I_R, R_L = 100 \Omega$ |

Notes:

- 6. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com.
- 7. Device mounted on Alumina PCB, 0.4 inch x 0.3 inch x 0.024 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com.

  8. Short duration pulse test used to minimize self-heating effect.



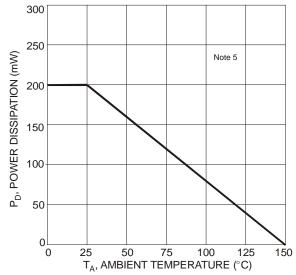
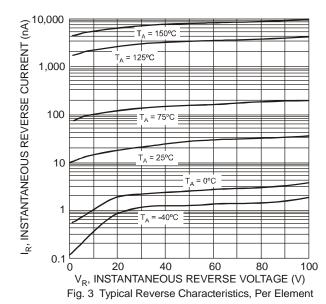


Fig. 1 Power Derating Curve, Total Package



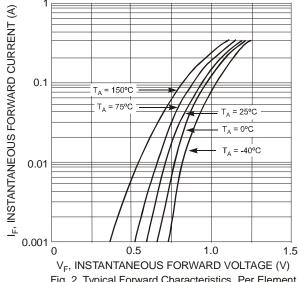


Fig. 2 Typical Forward Characteristics, Per Element

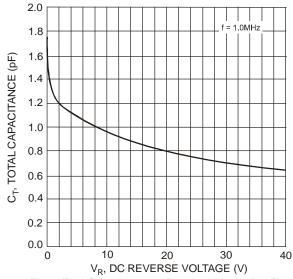
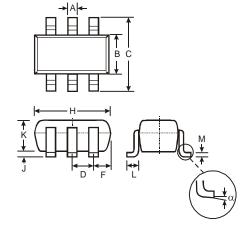


Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

## **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

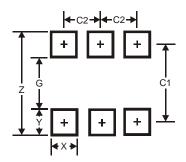


| SOT363               |          |      |  |  |
|----------------------|----------|------|--|--|
| Dim                  | Min      | Max  |  |  |
| Α                    | 0.10     | 0.30 |  |  |
| В                    | 1.15     | 1.35 |  |  |
| С                    | 2.00     | 2.20 |  |  |
| D                    | 0.65 Typ |      |  |  |
| F                    | 0.40     | 0.45 |  |  |
| Н                    | 1.80     | 2.20 |  |  |
| J                    | 0        | 0.10 |  |  |
| K                    | 0.90     | 1.00 |  |  |
| L                    | 0.25     | 0.40 |  |  |
| M                    | 0.10     | 0.22 |  |  |
| α                    | 0°       | 8°   |  |  |
| All Dimensions in mm |          |      |  |  |
|                      |          |      |  |  |



## Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| Z          | 2.5           |
| G          | 1.3           |
| Х          | 0.42          |
| Υ          | 0.6           |
| C1         | 1.9           |
| C2         | 0.65          |

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